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### IN THE UNITED STATES PATENT AND TRADEMARK OFFICE



Leonard Forbes et al.

## STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

Docket No.:

1303.109US1

July 21, 2003

Examiner:

Filed:

Pamela E. Perkins

Serial No.: 10/623,788

Due Date: December 18, 2006

Group Art Unit: 2822

#### MS Amendment

Commissioner for Patents

P.O. Box 1450

Alexandria, VA 22313-1450

We are transmitting herewith the following attached items (as indicated with an "X"):

- X Return postcard.
- $\underline{X}$  Amendment and Response (17 pgs.).
- X Communication Concerning Related Applications (2 pgs.).
- X Supplemental Information Disclosure Statement (2 pgs.), Form 1449 (1 pg.).
- $\underline{X}$ . Authorization to charge Deposit Account 19-0743 in the amount of \$180.00 to cover the fee for consideration of Information Disclosure Statement under 97(c).

If not provided for in a separate paper filed herewith, Please consider this a PETITION FOR EXTENSION OF TIME for sufficient number of months to enter these papers and please charge any additional fees or credit overpayment to Deposit Account No. 19-0743.

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

Customer Number 21186

Atty: Marvin L. Beekman

Reg. No. 38,377

CERTIFICATE UNDER 37 CFR 1.8: The undersigned hereby certifies that this correspondence is being deposited with the United States Postal Service with sufficient postage as first class mail, in an envelope addressed to: MS Amendment, Commissioner for Patents, P.O. Box 1450, Alexandria, VA 22313-1450, on this day of December, 2006.

Name

Signature

SCHWEGMAN, LUNDBERG, WOESSNER & KLUTH, P.A.

(GENERAL)

**PATENT** 

# IN THE UNITED STATES PATENT AND TRADEMARK OFFICE

Applicant: Leonard Forbes et al.

Examiner: Pamela E. Perkins

Serial No.:

10/623,788

Group Art Unit: 2822

Filed:

July 21, 2003

Docket: 1303.109US1

Title:

STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

# **COMMUNICATION CONCERNING RELATED APPLICATIONS**

## **MS** Amendment

Commissioner for Patents P.O. Box 1450 Alexandria, VA 22313-1450

Applicants would like to bring to the Examiner's attention the following related applications in the above-identified patent application:

Serial/Patent No. 11497632	Filing Date/Issue Date August 2, 2006	Attorney Docket 1303.186US1	Title STRAINED SEMICONDUCTOR, DEVICES AND SYSTEMS AND METHODS OF FORMATION
11475798	June 27, 2006	1303.109US2	STRAINED SEMICONDUCTOR BY FULL WAFER BONDING
11493128	July 26, 2006	1303.099US3	SEMICONDUCTORS BONDED ON GLASS SUBSTRATES
11460391	July 27, 2006	1303.103US2	GETTERING OF SILICON ON INSULATOR USING RELAXED SILICON GERMANIUM EPITAXIAL PROXIMITY LAYERS
11460398	July 27, 2006	1303.104US2	WAFER GETTERING USING RELAXED SILICON GERMANIUM EPITAXIAL PROXIMITY LAYERS
11494319	July 27, 2006	1303.102US3	STRAINED Si/SiGe/SOI ISLANDS AND PROCESSES OF MAKING SAME

Serial Number: 10/623,788 Filing Date: July 21, 2003

Title: STRAINED SEMICONDUCTOR BY FULL WAFER BONDING

Continuations and divisionals may be later filed on the cases listed above, or cited to the Examiner in any previous Communication Concerning Related Applications. Applicants request that the Examiner review all continuations and divisionals of the above-listed or previously-cited patent applications before allowing the claims of the present patent application.

Respectfully submitted,

LEONARD FORBES ET AL.

By Applicants' Representatives,

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Date /2 · 18 · 06

By Marvin L. Beekman

Reg. No. 38,377

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